

NEWS RELEASE

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Very High Performance DSP Module Family, Based on Intel® Xeon® Processor D, Debuted by Curtiss-Wright

New rugged 3U CHAMP-XD1 and 6U CHAMP-XD2 OpenVPX modules feature extremely fast DDR4 memory, 10/40 Gigabit Ethernet, and PCle Gen 3 interconnects

ASHBURN, Va. - April 20, 2015 - Curtiss-Wright Corporation (NYSE: CW) today announced that its Defense Solutions division has launched a new family of rugged DSP engine modules that is based on the Intel® Xeon® processor D (code-named "Broadwell-DE") product family and designed for use in very compute-intensive C4ISR aerospace and defense applications. The first members of the new CHAMP-XDx family, the 3U OpenVPX™ CHAMP-XD1 and 6U OpenVPX CHAMP-XD2, enable designers of High Performance Embedded Computing (HPEC) systems to take full advantage of the unmatched performance of today's leading-edge Xeon processor D architecture. Xeon processor D is Intel's first 3rd generation 64-bit SoC based on Xeon processor technology. These open architecture COTS modules feature high-speed DDR4 memory as well as high bandwidth PCIe Gen 3 data paths on both the data plane and the expansion plane. The new board family makes it easy for customers to extend their applications across different platforms, enabling system designers to fully leverage their investment in software development. To maximize system configuration flexibility, these size, weight, power and cost (SWaP-C) optimized modules also feature XMC card expansion and a combination of 1 Gigabit and 10 Gigabit Ethernet (GbE) interfaces. The CHAMP-XDx module family is designed for the most demanding defense and aerospace rugged deployed HPEC systems. including next-generation Radar, EW and a wide range of C4ISR applications.

"Curtiss-Wright fully understands the challenges our customers face in building their next generation Intelligence, Surveillance and Reconnaissance (ISR) systems," said Lynn Bamford, Senior Vice President and General Manager, Defense Solutions division. "The CHAMP-XD1 and CHAMP-XD2 boards unleash the full power of the Intel Xeon processor D family, driving sophisticated applications with very high throughput, low latency requirements. Providing both 3U and 6U variants, the CHAMP-XDx family enables system integrators to extend their investments in software across multiple platforms and applications."

Both the CHAMP-XD1 and the CHAMP-XD2 will be available in a range of ruggedized configurations to deliver optimal performance in the harshest deployed environments, including air-cooled and conduction-cooled versions. Leveraging Curtiss-Wright's extensive 3U OpenVPX ecosystem, the CHAMP-XD1 forms the centerpiece of new small-form factor HPEC system architectures. In addition to its extremely fast DDR4 memory, and support for 1/10 GbE, the CHAMP-XD1 also provides PCIe Gen 3 on the 3U Data Plane. The dual-processor CHAMP-XD2 brings the performance of two independent Xeon D processors to a single 6U chassis slot. It supports either 40 GbE or InfiniBand on the Data Plane in addition to its 1 GbE and 10 GbE interfaces.

The CHAMP-XD1 and CHAMP-XD2 are scheduled for availability starting Q4 2015.

Sales inquiries: Please forward all Sales and reader service inquiries to Kavita Williams, Curtiss-Wright Defense Solutions, Tel: (661) 705-1142; Fax: (661) 705-1206; email: ds@curtisswright.com.

For more information on Curtiss-Wright Defense Solutions products, please visit www.curtisswrightds.com.

About Curtiss-Wright Corporation

Curtiss-Wright Corporation (NYSE:CW) is a global innovative company that delivers highly engineered, critical function products and services to the commercial, industrial, defense and energy markets. Building on the heritage of Glenn Curtiss and the Wright brothers, Curtiss-Wright has a long tradition of providing reliable solutions through trusted customer relationships. The company employs approximately 9,000 people worldwide. For more information, visit www.curtisswright.com.

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